



## **Applied Materials to Acquire Wafer Clean Technology from SCP**

June 28, 2005

SANTA CLARA, Calif.--(BUSINESS WIRE)--June 28, 2005--Applied Materials, Inc., the world's largest supplier of wafer fabrication solutions to the global semiconductor industry, today announced the signing of a definitive agreement with SCP Global Technology, Inc. to acquire SCP's single-wafer HF-last immersion technology and Marangoni(R) clean/dry intellectual property. Marangoni clean/dry technology is an industry standard for 65nm and below wet clean processing. This acquisition complements Applied Materials' current wet cleaning product and provides an expanded range of advanced cleaning solutions for customers' critical applications.

"The intrinsic capability of single-wafer technology to clean substrates more uniformly and reduce cross-contamination has compelling performance and yield advantages for both front-end of the line and back-end process requirements," said John T.C. Lee, general manager of Applied Materials' Cleans Product Group. "We look forward to bringing a new level of cleaning capabilities to customers."

Applied Materials, Inc. (Nasdaq:AMAT), headquartered in Santa Clara, California, is the largest supplier of equipment and services to the global semiconductor industry. Applied Materials' Website is <http://www.appliedmaterials.com>.

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